

High Performance BGA Cooling Solutions w/ maxiGRIP™ Attachment*

DIGI-KEY PART # ATS1178-ND

ATS PART # ATS-53450K-C2-R0

Features & Benefits

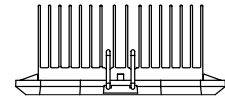
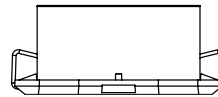
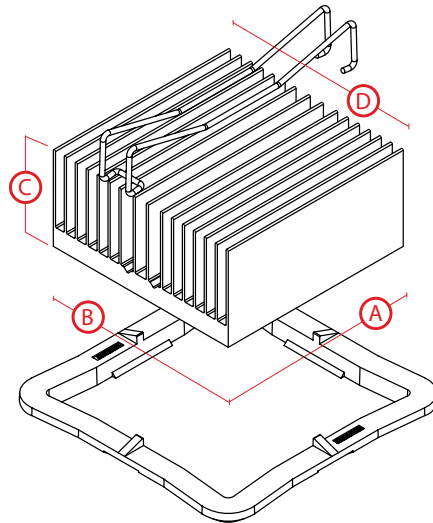
High aspect ratio, straight fin heat sinks that are ideal for compact PCB environments

maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB

Designed specifically for BGAs and other surface mount packages

Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock Testing and Unpackaged Drop Testing standards

Comes preassembled with high performance thermal interface material



Thermal Performance Table

| AIR VELOCITY | | THERMAL RESISTANCE | |
|--------------|-----|--------------------|---------------|
| FT/MIN | M/S | °C/W (UNDUCTED) | °C/W (DUCTED) |
| 200 | 1.0 | 4.1 | 1.9 |
| 300 | 1.5 | 2.8 | |
| 400 | 2.0 | 2.3 | |
| 500 | 2.5 | 2 | |
| 600 | 3.0 | 1.8 | |
| 700 | 3.5 | 1.7 | |
| 800 | 4.0 | 1.6 | |

Product Details†

| DIMENSION A | DIMENSION B | DIMENSION C§ | DIMENSION D | TIM‡ | FINISH |
|-------------|-------------|--------------|-------------|------|----------------|
| 45 | 45 | 14.5 | N/A | C675 | BLACK-ANODIZED |

For further technical information, please contact Advanced Thermal Solutions, Inc. at **1-781-769-2800** or **www.qats.com**

* RoHS Compliant

‡ TIM = Thermal Interface Material

† Dimensions are measured in millimeters

♦ Dimensions A & B refer to component size

§ Dimension C = the height of the heat sink shown above and does not include the height of the attachment method



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